

Electronic Acknowledgement Receipt

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Title of Invention:	Novel method to improve bump reliability for flip chip device
First Named Inventor:	Yen-Ming Chen
Customer Number:	47390
Filer:	Daniel R. McClure
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Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Amendment After Final	00394666.pdf	142800	no	9

Warnings:	
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